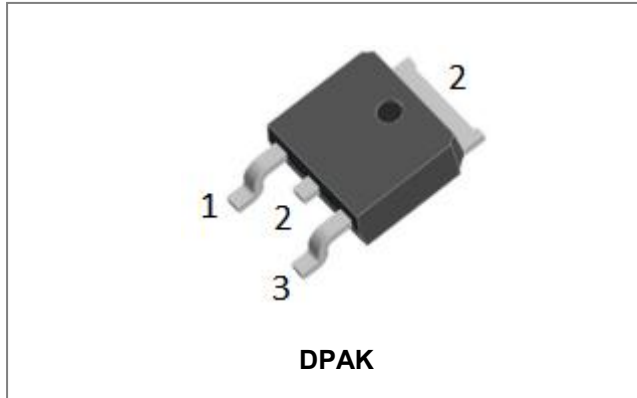


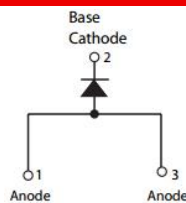
MBRD360 THRU MBRD3200 SCHOTTKY RECTIFIER



Features

- 150°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb - Free Device
- "-A" is an AEC-Q101 qualified device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Disk drives
- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection
- Battery charging

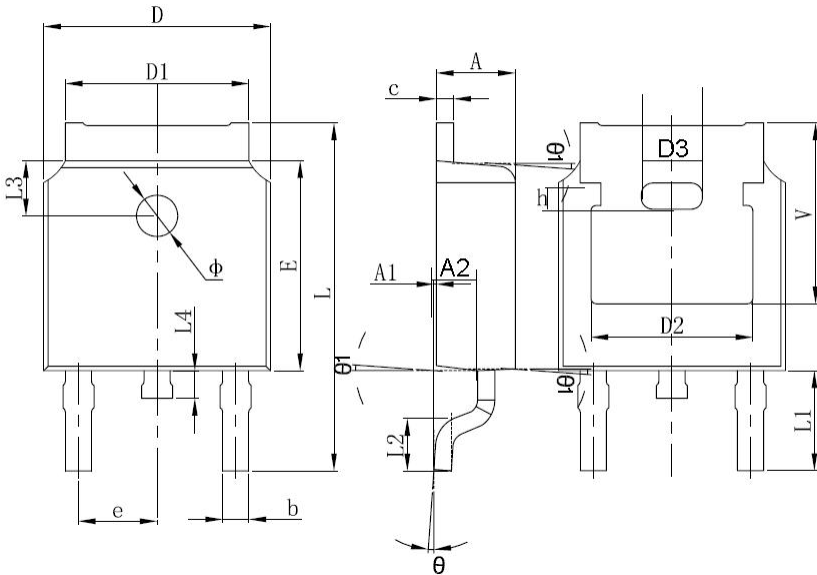
Maximum Ratings and Electrical characteristics @T_A = 25°C unless otherwise specified

Characteristics	Symbol	MBRD 360	MBRD 380	MBRD 3100	MBRD 3150	MBRD 3200	Units
Peak Repetitive Reverse Voltage	V _{RRM}						
Working Peak Reverse Voltage	V _{RWM}	60	80	100	150	200	V
DC Blocking Voltage	V _R						
Average Forward Current	I _{F(AV)}	3					A
Max. Peak One Cycle Non-Repetitive Surge Current(8.3ms Single half sine-wave)	I _{FSM}	80					A
Max. Forward Voltage Drop* @3A, 25°C	V _F	0.65	0.75	0.85	0.90	0.92	V
Max. Reverse Current* @V _{RWM} , 25°C	I _R	1					mA
Max. Junction Capacitance(Note1)	C _T	250			100		pF
Junction Temperature	T _J	-55 to +150					°C
Storage Temperature	T _{stg}	-55 to +150					°C
Typical Thermal Resistance Junction to Case (DC operation)	R _{θJC}	6.0					°C/W
Approximate Weight	wt	0.39					g
Case Style		DPAK					

* Pulse width < 300 μs, duty cycle < 2%

Note1: Measured at 1.0 MHz and applied reverse voltage of 5.0V D.C.

Mechanical Dimensions DPAK



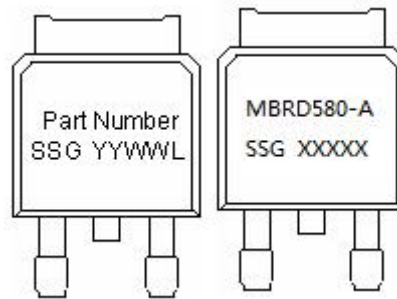
SYMBOL	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.20	2.40	0.087	0.094
A1	0.00	0.127	0.000	0.005
b	0.66	0.86	0.026	0.034
c	0.46	0.60	0.018	0.024
D	6.50	6.70	0.256	0.264
D1	5.13	5.46	0.202	0.215
D2	4.83 REF.		0.190 REF.	
E	6.00	6.20	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.70	10.40	0.381	0.409
L1	2.90 REF.		0.144 REF.	
L2	1.40	1.70	0.055	0.067
L3	1.60 REF.		0.063 REF.	
L4	0.60	1.00	0.024	0.039
Φ	1.10	1.30	0.043	0.051
θ	0°	8°	0°	8°
h	0.00	0.30	0.000	0.012
V	5.35 REF.		0.211 REF.	

Ordering Information

Device	Package	Shipping
MBRD360 THRU MBRD3200	DPAK (Pb-Free)	2500pcs / reel

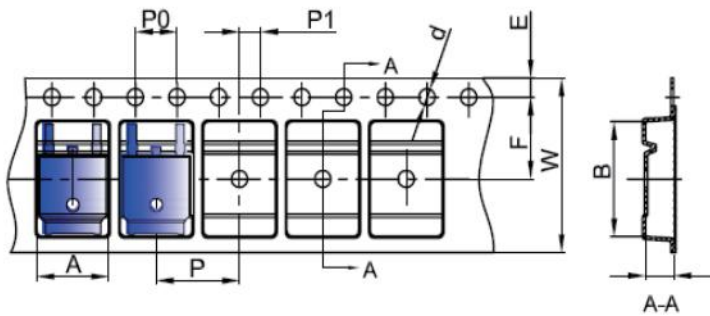
For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

Marking Diagram



First row: Part Number (MBRD360, MBRD380, MBRD3100, MBRD3150, MBRD3200)
 -A = AEC-Q101
 Second row: SSG YYWWL
 YY is the manufacture year, WW is the manufacture week code, L is the wafer's Lot Number

Carrier Tape Specification DPAK



SYMBOL	Millimeters	
	Min.	Max.
A	6.80	7.00
B	10.40	10.60
C	2.60	2.80
d	Φ1.45	Φ1.65
E	1.65	1.85
F	7.40	7.60
P0	3.90	4.10
P	7.90	8.10
P1	1.90	2.10
W	15.90	16.30

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